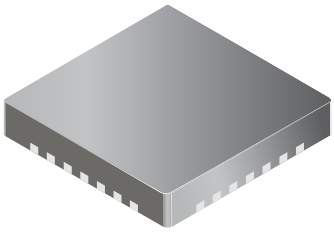
3-Phase Brushless DC Motor Pre-Driver

Features and Benefits

- Drives 6 N-channel MOSFETs
- Synchronous rectification for low power dissipation
- Internal UVLO and thermal shutdown circuitry
- Hall element inputs
- PWM current limiting
- Dead time protection
- FG outputs
- Standby mode
- Lock detect protection
- Overvoltage protection

Package: 28-contact QFN (ET package)



Approximate Scale 1:1

Description

The A4938 is a complete 3-phase brushless DC (BLDC) motor pre-driver, supplying direct, high-current gate drive of an all N-channel power MOSFET 3-phase bridge. The device has three Hall-element inputs, a sequencer for commutation control, fixed off-time pulse width modulation (PWM) current control, and locked-rotor detection.

Output current is scaled by the capability of the external MOSFETs. Locked rotor detection delay is set by an external capacitor on the CLD terminal. The ENABLE, DIR, and BRAKEZ inputs can be used to control motor speed, position, and torque. Motor speed can be determined using the FG1 output.

The external MOSFETS can be PWMed using an external signal on the PWM input, or using the internal PWM current regulator. In either case, the A4938 synchronous rectification feature reduces power dissipation by turning on the appropriate MOSFETs during current decay.

The Hall elements can be inexpensive types, when used with noise filtering to prevent false commutation signals. The A4938 provides a regulated 5.0 V supply to power the three Hall elements. Internal circuit protection includes thermal

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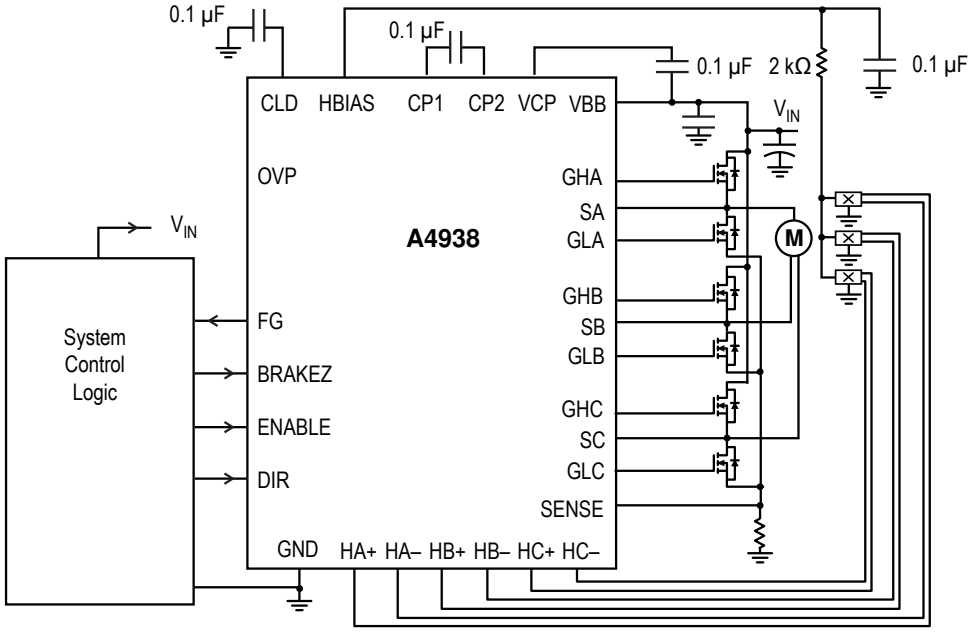
Typical Application



Description (continued)

shutdown with hysteresis, undervoltage lockout, and dead time protection. Special power-up sequencing is not required. Operating temperature range is –40°C to 85°C.

The A4938 is supplied in a 5 mm × 5 mm, 28-terminal QFN package with exposed thermal pad. This small footprint package is lead (Pb) free with 100% matte tin leadframe plating.

Selection Guide

Part Number	Packing	Package
A4938EETTR-T	1500 pieces per reel	5 mm x 5 mm, 0.90 mm nominal height QFN

Absolute Maximum Ratings

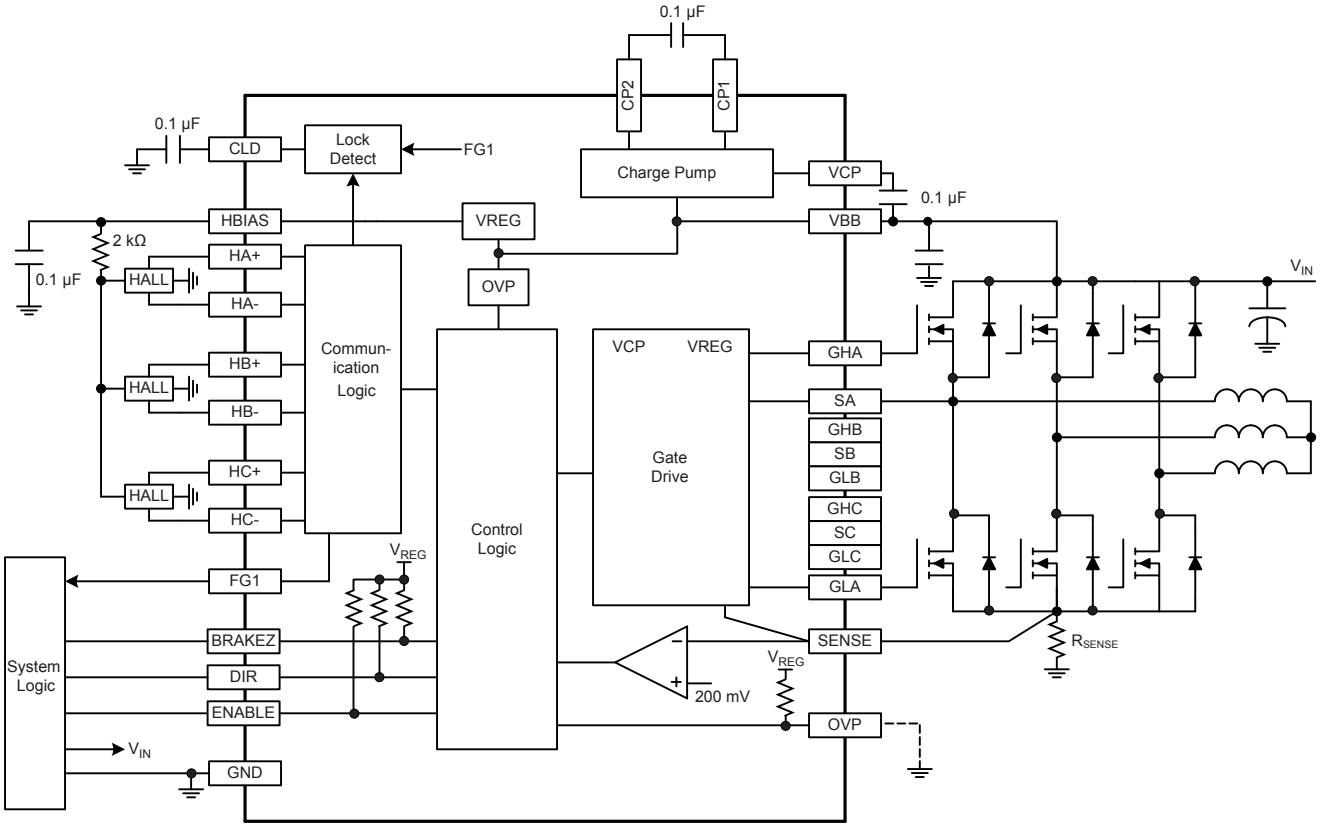
Characteristics	Symbol	Notes	Rating	Unit
Load Supply Voltage	V_{BB}		38	V
Motor Phase Output	S_X	t_w < 500 ns	–3	V
Hall Input	V_{Hx}	DC	–0.3 to 7	V
Logic Input Voltage Range	V_{IN}		–0.3 to 7	V
Operating Ambient Temperature	T_A	Range E	–40 to 85	ºC
Maximum Junction Temperature	T_J(max)		150	ºC
Storage Temperature	T_{stg}		–40 to 150	ºC

Thermal Characteristics

Characteristics	Symbol	Test Conditions*	Rating	Unit
Package Thermal Resistance, Junction to Ambient	$R_{\theta JA}$	4-layer PCB based on JEDEC standard	32	ºC/W
Package Thermal Resistance, Junction to Exposed Pad	$R_{\theta JP}$		2	ºC/W

*For additional information, refer to the Allegro website.

Functional Block Diagram



Terminal List

Number	Name	Description
1	HA+	Hall input A
2	HA -	Hall input A
3	HB+	Hall input B
4	HB -	Hall input B
5	HC+	Hall input C
6	HC-	Hall input C
7	GND	Ground
8	HBIAS	Hall bias power supply output
9	CP1	Charge pump capacitor terminal
10	CP2	Charge pump capacitor terminal
11	VBB	Supply voltage
12	VCP	Reservoir capacitor terminal
13	SENSE	Sense resistor connection
14	GLC	Low side gate drive C

Number	Name	Description
15	GLB	Low side gate drive B
16	GLA	Low side gate drive A
17	GHC	High side gate drive C
18	SC	High side source connection C
19	GHB	High side gate drive B
20	SB	High side source connection B
21	GHA	High side gate drive A
22	SA	High side source connection A
23	FG1	FG 1 output
24	OVP	Logic input – OVP selection
25	CLD	Locked rotor detect timing capacitor
26	DIR	Logic input – motor direction
27	ENABLE	Logic input – external PWM control
28	BRAKEZ	Logic input – motor brake (active low)

ELECTRICAL CHARACTERISTICS[*] Valid at T_A= 25°C, V_{BB} = 24 V, unless noted otherwise

Characteristics	Symbol	Test Conditions	Min.	Typ.	Max.	Unit
Supply Voltage Range	V_{BB}	Operating	8.5	–	30	V
Motor Supply Current	I_{BB}	f_{PWM} < 30 kHz, C_{LOAD} = 1000 pF	–	5	6	mA
		Charge pump on, outputs disabled, Standby mode	–	2.4	3.2	mA
HBIAS	V_{HBIAS}	0 mA ≤ I_{HBIAS} ≤ 24 mA	4.7	5.0	5.3	V
HBIAS Current Limit	$I_{HBIASlim}$		35	–	–	mA
Control Logic						
Logic Input Voltage	$V_{IN(1)}$		2	–	–	V
	$V_{IN(0)}$		–	–	0.8	V
Logic Input Pull-Up	$R_{IN(PU)}$	OVP pin pull-up to HBIAS	–	100	–	kΩ
		ENABLE, BRAKEZ, DIR pins pull-up to HBIAS	–	50	–	kΩ
Input Pin Glitch Reject	t_{GLITCH}	ENABLE pin	350	500	650	ns
		DIR, BRAKEZ pins	700	1000	1300	ns
ENABLE Standby Pulse Propagation Delay	$t_{dENABLE}$	To outputs off	2.1	3	3.9	ms
HBIAS Wake-up Delay, Standby Mode	t_{dHBIAS}	C_{HBIAS} = 0.1 µF	–	15	25	µs
Gate Drive						
High-Side Gate Drive Output	$V_{GS(H)}$	Relative to V_{BB}, I_{GATE} = 2 mA	7	–	–	V
Low-Side Gate Drive Output	$V_{GS(L)}$	I_{GATE} = 2 mA	4.5	–	–	V
Gate Drive Current (Sourcing)	I_{Gate}	GH = GL = 4 V	20	30	–	mA
Gate Drive Pull Down Resistance	R_{Gate}		10	28	40	Ω
Dead Time	t_{dead}		700	1000	1300	ns
Current Limit Input Threshold	V_{REF}		180	200	220	mV
Fixed Off-Time	t_{OFF}		18	25	37	µs
Protection						
Thermal Shutdown Temperature	T_{JTSD}		155	170	185	°C
Thermal Shutdown Hysteresis	$T_{JTSDhys}$		–	20	–	°C
VBB UVLO Enable Threshold	V_{BBUV}	Rising V_{BB}	6.20	7	7.85	V
VBB UVLO Hysteresis	$V_{BBUVhys}$		0.4	0.75	1	V
VCP UVLO	V_{CPUV}	Relative to V_{BB}	4.6	–	6	V
Lock Detect Duration	t_{lock}	C = 0.1 µF	1.5	2	2.5	s
VBB Overvoltage Threshold	V_{BBOV}	OVP = GND, V_{BB} rising	15.5	16	16.5	V
		OVP = open, V_{BB} rising	28.5	29	29.5	V
VBB Overvoltage Hysteresis	V_{OVOhys}		–	2	–	V

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ELECTRICAL CHARACTERISTICS* (continued) Valid at T_A= 25°C, V_{BB} = 24 V, unless noted otherwise

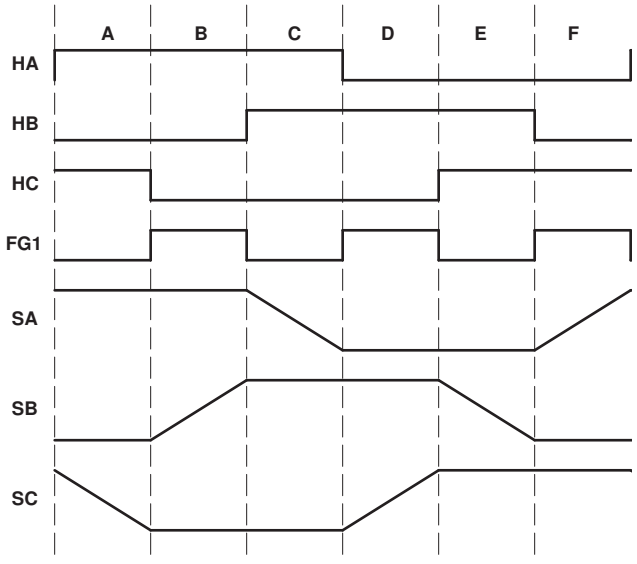
Characteristics	Symbol	Test Conditions	Min.	Typ.	Max.	Unit
Hall Logic						
Hall Input Current	I_{HALL}	V_{IN} = 0.2 to 3.5 V	–1	0	1	µA
Common Mode Input Range	V_{CMR}		0.2	–	2.0	V
AC Input Voltage Range	V_{HALL}		60	–	–	mV_{p-p}
Hall Thresholds	V_{th}	Difference between Hall inputs at transitions	–	+10,–10	–	mV
Hall Threshold Hysteresis	V_{HYS}	T_J = 25°C	10	20	30	mV
		T_J = –40°C to 125°C	5	20	40	mV
Pulse Reject Filter	t_{pulse}		–	2	–	µs
FG						
FG Output Saturation Voltage	$V_{FG(sat)}$	I_{FG} = 2 mA	–	–	0.5	V
FG Leakage Current	I_{FGlkg}	V_{FG} = 5 V	–	–	1	µA

*Typical data are for initial design estimations only, and assume optimum manufacturing and application conditions. Performance may vary for individual units, within the specified maximum and minimum limits.
For input and output current specifications, negative current is defined as coming out of (sourcing) the specified device pin.
Specifications throughout the allowed operating temperature range are guaranteed by design and characterization.

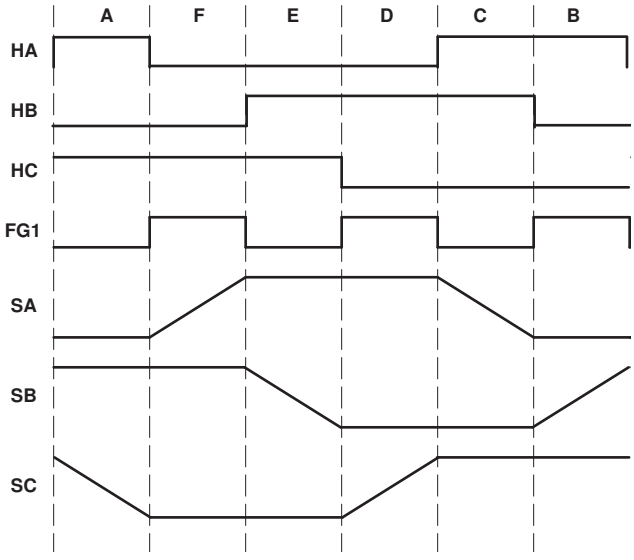
Logic States Table (See timing charts, below) X = Don't Care (can be 1 or 0), Z = high impedance

Condition		Inputs						Resulting Pre-Driver Outputs						Motor Output		
		HA	HB	HC	DIR	BRAKEZ	ENABLE	GHA	GLA	GHB	GLB	GHC	GLC	A	B	C
Forward	A	+	–	+	1	1	0	HI	LO	LO	HI	LO	LO	HI	LO	Z
	B	+	–	–	1	1	0	HI	LO	LO	LO	LO	HI	HI	Z	LO
	C	+	+	–	1	1	0	LO	LO	HI	LO	LO	HI	Z	HI	LO
	D	–	+	–	1	1	0	LO	HI	HI	LO	LO	LO	LO	HI	Z
	E	–	+	+	1	1	0	LO	HI	LO	LO	HI	LO	LO	Z	HI
	F	–	–	+	1	1	0	LO	LO	LO	HI	HI	LO	Z	LO	HI
Reverse	A	+	–	+	0	1	0	LO	HI	HI	LO	LO	LO	LO	HI	Z
	F	+	–	–	0	1	0	LO	HI	LO	LO	HI	LO	LO	Z	HI
	E	+	+	–	0	1	0	LO	LO	LO	HI	HI	LO	Z	LO	HI
	D	–	+	–	0	1	0	HI	LO	LO	HI	LO	LO	HI	LO	Z
	C	–	+	+	0	1	0	HI	LO	LO	LO	LO	HI	HI	Z	LO
	B	–	–	+	0	1	0	LO	LO	HI	LO	LO	HI	Z	HI	LO
Chop	A	+	–	+	X	1	If 1 for <3 ms	LO	HI	LO	HI	LO	LO	LO	LO	Z
	F	+	–	–	X	1	If 1 for <3 ms	LO	HI	LO	LO	LO	HI	LO	Z	LO
	E	+	+	–	X	1	If 1 for <3 ms	LO	LO	LO	HI	LO	HI	Z	LO	LO
	D	–	+	–	X	1	If 1 for <3 ms	LO	HI	LO	HI	LO	LO	LO	LO	Z
	C	–	+	+	X	1	If 1 for <3 ms	LO	HI	LO	LO	LO	HI	LO	Z	LO
	B	–	–	+	X	1	If 1 for <3 ms	LO	LO	LO	HI	LO	HI	Z	LO	LO
Fault		–	–	–	X	X	X	LO	LO	LO	LO	LO	LO	Z	Z	Z
		+	+	+	X	X	X	LO	LO	LO	LO	LO	LO	Z	Z	Z
Brake		X	X	X	X	0	If 0, or if 1 for < 3 ms	LO	HI	LO	HI	LO	HI	LO	LO	LO
Standby		X	X	X	X	X	If 1 for >3 ms	LO	LO	LO	LO	LO	LO	Z	Z	Z

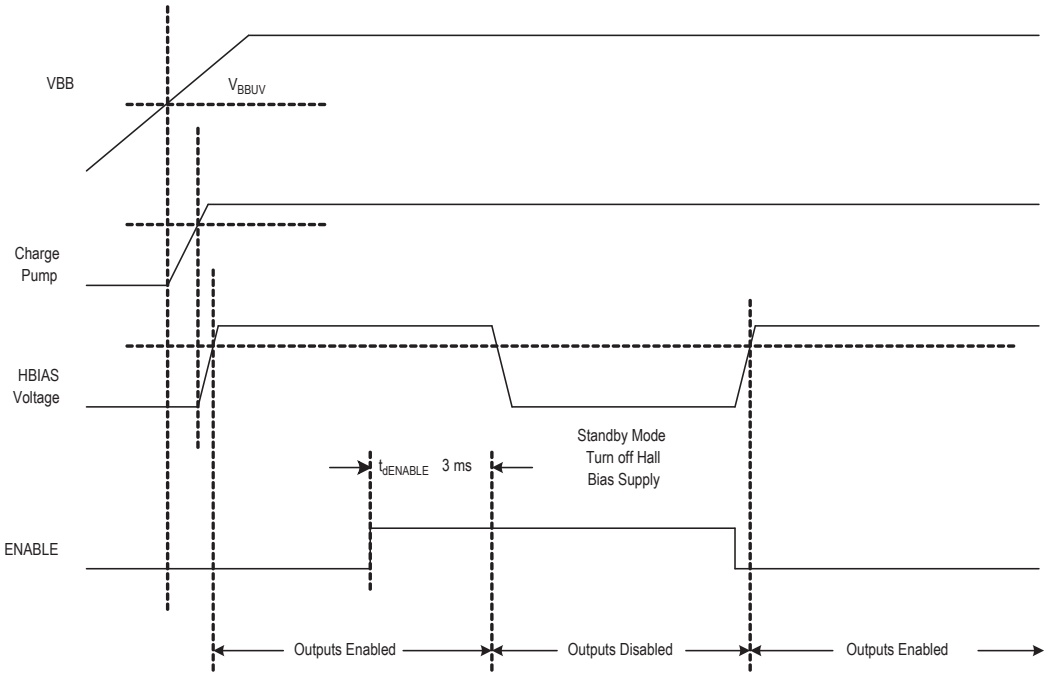
DIR = 1 = Forward



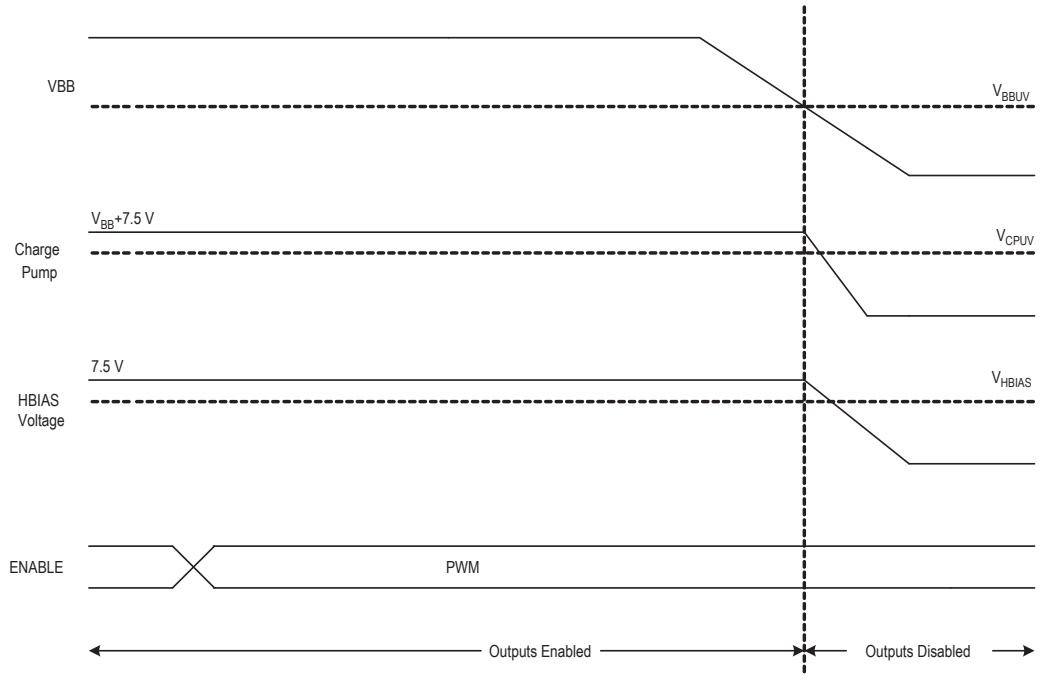
DIR = 0 = Reverse



Power-up and Standby Modes Timing Diagram



Power-up and Standby Modes Timing Diagram



Functional Description

Current Regulation Load current is regulated by an internal fixed off-time PWM control circuit. When the outputs of the full bridge are turned on, current increases in the motor winding until it reaches a value, I_{TRIP}, given by:

$$I_{TRIP} = 200 \text{ mV} / R_{SENSE} .$$

When I_{TRIP} is reached, the sense comparator resets the source enable latch, turning off the source driver. At this point, load inductance causes the current to recirculate for the fixed off-time period.

Enable Logic The ENABLE pin allows external PWM. ENABLE low turns on the selected sink-source pair. ENABLE high switches off the appropriate drivers and the load current decays. If ENABLE is held low, the current will rise until it reaches the level set by the internal current control circuit. Typically PWM frequency is in the 20 to 30 kHz range. If the ENABLE high pulse width exceeds 3 ms, the gate outputs are disabled. The Enable logic is summarized in the following table:

ENABLE Pin	Outputs	Outputs State
0	On	Drive
1	Source chopped	Slow decay with synchronous rectification
1 for > 3 ms typical	Off	Disable

Fixed Off-Time The A4938 fixed off-time is set to 25 µs nominal.

PWM Blank Timer When a source driver turns on, a current spike occurs due to the reverse recovery currents of the clamp diodes and/or switching transients related to distributed capacitance in the load. To prevent this current spike from erroneously resetting the source Enable latch, the sense comparator is blanked. The blanking timer runs after the off-time counter, to provide the blanking function. The blanking timer is reset when ENABLE is chopped or DIR is changed. For external PWM control, a DIR change or an ENABLE on triggers the blanking function. The duration is fixed at 1.5 µs.

Synchronous Rectification When a PWM-off cycle is triggered, either by an ENABLE chop command or by an internal fixed off-time cycle, load current recirculates. The A4938 synchronous rectification feature turns on the appropriate MOSFETs during the current decay, and effectively shorts out the body diodes with the low $R_{DS(on)}$ driver. This lowers power dissipation significantly and can eliminate the need for external Schottky diodes.

Brake Mode A logic low on the BRAKEZ pin activates Brake mode. A logic high allows normal operation. Braking turns on all three sink drivers, effectively shorting out the motor-generated BEMF. The BRAKEZ input overrides the ENABLE input and also the Lock Detect function.

It is important to note that the internal PWM current control circuit does not limit the current when braking, because the current does not flow through the sense resistor. The maximum current can be approximated by V_{BEMF} / R_{LOAD}. Care should be taken to insure that the maximum ratings of the A4938 are not exceeded in the worse case braking situation: high speed and high inertial load.

HBIAS Function This function provides a power supply of 5.0 V, current-limited to 35 mA. This reference voltage is used to power the logic sections of the A4938 and also to power the external Hall elements.

Standby Mode To prevent excessive power dissipation due to the current draw of the external Hall elements, Standby mode turns off the HBIAS output voltage. Standby mode is triggered by

holding ENABLE high for longer than 3 ms. Note that the state of BRAKEZ does not affect Standby mode.

Charge Pump The internal charge pump is used to generate a supply above V_{BB} to drive the high-side MOSFETs. The voltage on the VCP pin is internally monitored, and in the case of a fault condition, the outputs of the device are disabled.

Fault Shutdown In the event of a fault due to excessive junction temperature, or due to low voltage on VCP or VBB, the outputs of the device are disabled until the fault condition is removed. At power-up the UVLO circuit disables the drivers.

Overvoltage Protection VBB is monitored to determine if a hazardous voltage is present due to the motor generator pumping-up the supply bus. When the voltage exceeds V_{BBOV}, the synchronous rectification feature is disabled. Connecting OVP to GND sets V_{BBOV} to 16 V typically, and leaving OVP open sets V_{BBOV} to 29 V typically.

Overtemperature Protection If die temperature exceeds approximately 170°C, the Thermal Shutdown function will disable the outputs until the internal temperature falls below the threshold hysteresis.

Hall State Reporting The FG1 pin is an open drain output that changes state at each transition of an external Hall element.

Lock Detect Function The IC will evaluate a locked rotor condition under either of these two different conditions:

- The FG1 signal is not consistently changing.
- The proper commutation sequence is not being followed. The motor can be locked in a condition in which it toggles between two specific Hall device states.

Both of these fault conditions are allowed to persist for a period of time, t_{lock}. The value of t_{lock} is set by capacitor connected to the CLD pin. C_{LD} produces a triangle waveform (1.67 V peak-to-peak) with a frequency linearly related to the capacitor value. t_{lock} is defined as 127 cycles of this triangle waveform, or:

$$t_{lock} = C_{LD} \times 20 \text{ s/}\mu\text{F}$$

After the wait time, t_{lock}, has expired, the outputs are disabled, and the fault is latched.

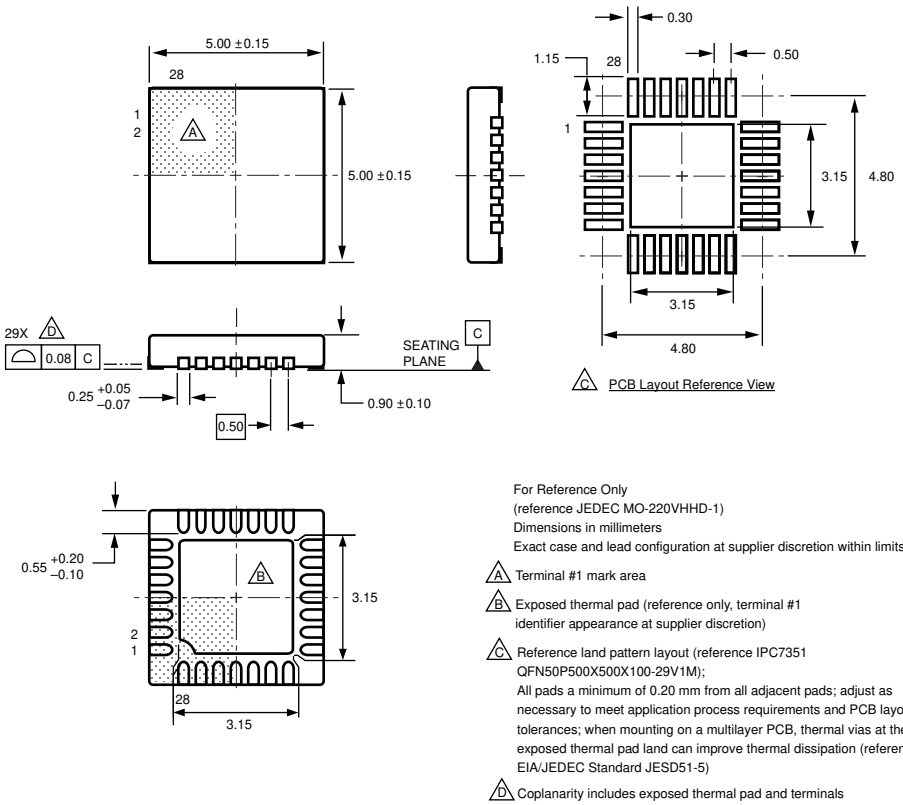
These fault conditions are latched and can only be cleared by any one of the following actions:

- Rising or falling edge on the DIR pin
- VBB UVLO threshold exceeded (during power-up cycle)
- ENABLE pin held high for > t_{lock} / 2

The Lock Detect function can be disabled by connecting CLD to GND.

When the A4938 is in Brake mode, the Lock Detect counter is disabled.

ET Package, 28-Contact QFN



For Reference Only
(reference JEDEC MO-220VHHD-1)
Dimensions in millimeters
Exact case and lead configuration at supplier discretion within limits shown

A Terminal #1 mark area

B Exposed thermal pad (reference only, terminal #1 identifier appearance at supplier discretion)

C Reference land pattern layout (reference IPC7351 QFN50P500X500X100-29V1M);
All pads a minimum of 0.20 mm from all adjacent pads; adjust as necessary to meet application process requirements and PCB layout tolerances; when mounting on a multilayer PCB, thermal vias at the exposed thermal pad land can improve thermal dissipation (reference EIA/JEDEC Standard JESD51-5)

D Coplanarity includes exposed thermal pad and terminals

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